

SMT ADHESIVE – Heat Cure Type

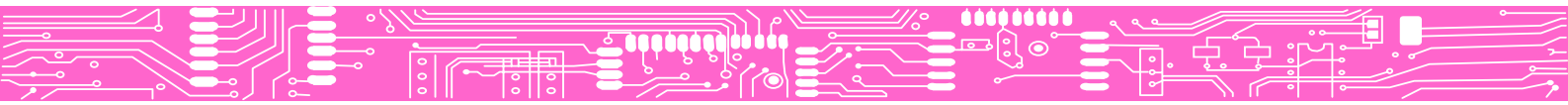
JU-100-5 series

■ Features

1. Excellent dispensability at both slow or extremely fast dispensing speeds (0.08sec./dot).
2. High slump resistance whilst dispensing and also during the heat curing process.
3. Very high dot profile.
4. Availability in extensive range of packaging options.

■ Specifications

	Application		Dispense		
	Product		JU-100-5	JU-100-5W	
Before curing	Composition		Epoxy		
	State • Color		Paste • Red	Paste • white	
	Specific gravity		1.21	1.22	
	Viscosity (Pa.s • 20°C)		50	50	
	Thixotropy (20°C)		5.5	5.5	
	Non-volatile (105°C • 3 hr)		>99 %	>99 %	
	Shelf life	At room temp. (20°C)		1 month	
		Below 10°C		6 months	
	Bonding strength	2125 square chip		>3 kg	>3 kg
Minimold Tr		>3 kg	>3 kg		
Copper plate corrosion (40°C× 95%RH×96hr)		Passed	Passed		
Heat resistivity (250°C × 10sec.)		Passed	Passed		
After curing	Surface insulation resistant	Initial value (Ω)	$> 1 \times 10^{12}$	$> 1 \times 10^{12}$	
		40°C, 95%RH× 96hr (Ω)	$> 1 \times 10^{11}$	$> 1 \times 10^{11}$	
	Water absorption (boiling water 1 hour)		< 0.17	< 0.15	
	Dielectric constant (1 MHz)		3.7	3.8	
	Dielectric tangent (1 MHz)		0.02	0.02	
	Linear expansion coefficient (cm/cm • °C)		7.9×10^{-5}	7.9×10^{-5}	
	Solvent resistivity (dipping x 1hr; IPA, glycol)		No abnormality	No abnormality	



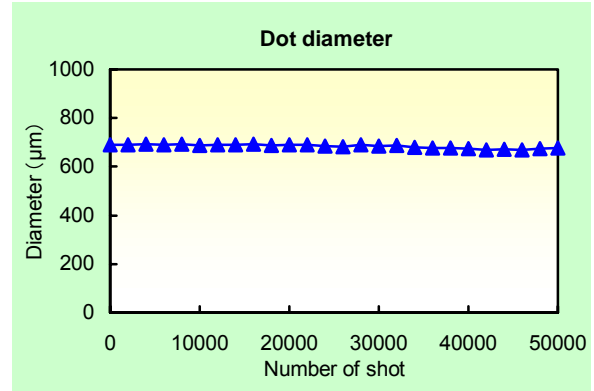
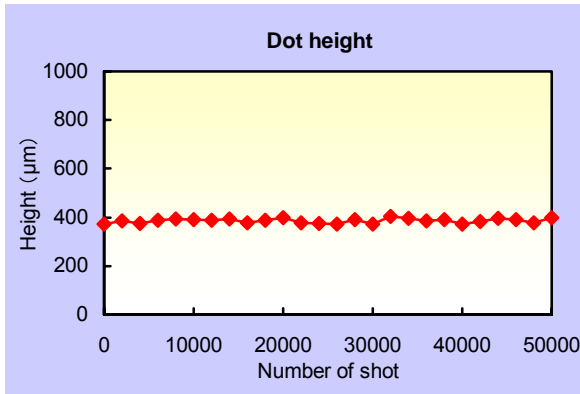
■ Dispensing temperature

Optimum results will be obtained at a constant controlled temperature of 30~ 35°C.

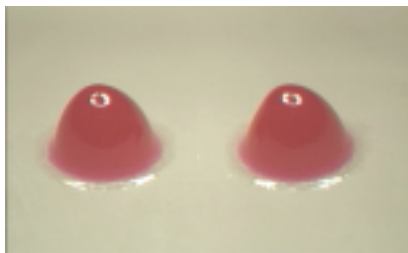
■ Curing condition

- 120 ~ 130°C × over 90sec.
- 130 ~ 150°C × over 60sec

■ Dispense stability (Nozzle : twin 22G)

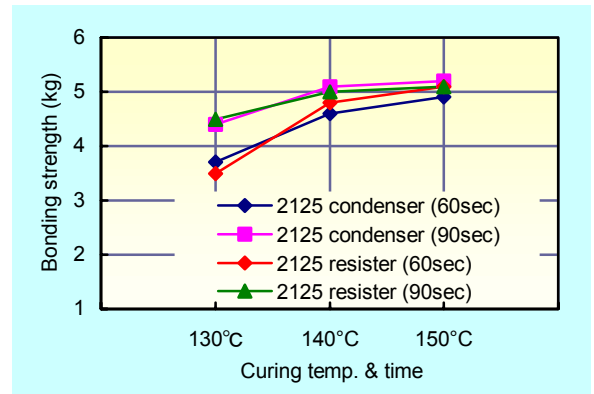


■ Dot profile (Nozzle : twin 22G)

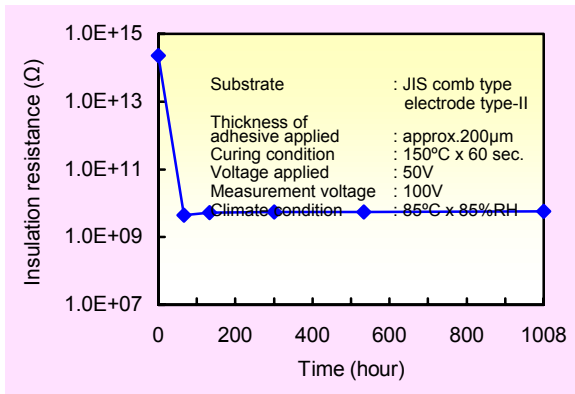


Dot profile at 50,000th shots

■ Bonding strength



■ Surface insulation resistance



■ Packaging

Available in various types of syringe (10cc, 20cc, 25cc, 30cc)

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